

Amphenol ICC

ExpressPort® SFP+

Amphenol ICC's ExpressPort® SFP+ interconnect system provides data transfer speeds of up to 16Gb/s. The design of the ExpressPort® SFP+ connector minimizes impedance discontinuities and reflections at high data rates and provides a 10 to 20 dB improvement in Near-End Crosstalk. The ExpressPort® SFP+ unique cage construction features EMI shielding available in the form of metal spring fingers or elastomeric gaskets. Additional features available include light pipes, heat sinks and many other custom features.

TECHNICAL INFORMATION

MATERIAL

- Housing: Black or nature color, Glass-reinforced, lead-free solder reflow process compatible thermoplastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin or gold flash options
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 50 N max.
- Card Entry Slot: 1.0mm-thick integrated circuit cards
- Contact Normal Force: 100 grams
- PCB Thickness Single Side (Cage): 1.57 mm (0.062 in.) min.
- PCB Thickness Belly to Belly (Cage): 3.00 mm (0.118 in.) min.
- Unmating Force (Cage): 11.50 N max.
- Insertion Force to PCB (Cage):
- 1000 N for 2 port
- 2100 N for 4 port
- 3000 N for 6 port

4 port

ELECTRICAL PERFORMANCE

Operating Voltage: 30 VDC per contact

TARGET MARKETS

- Operating Current: 0.5 A per contact
- Differential Impedance: 100 Ω +/- 10 Ω

ENVIRONMENTAL

- Operating and (Storage) Temperature: -55° to +85°C
- RoHS & Halogen-Free

TOOLING INFORMATION

- EMI Options, Heat Sink and Clip: Available
- Configurations:
 - 1xN (N = 1,2,3,4,5,6,8)
 - 2xN (N = 1,2,3,4,5,6,8)

TARGET MARKETS/APPLICATIONS



Cellular Infrastructure Network Interface Cards Switch

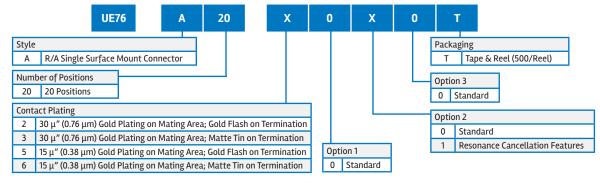
Hubs Servers Storage

Test and Measurement Equipment

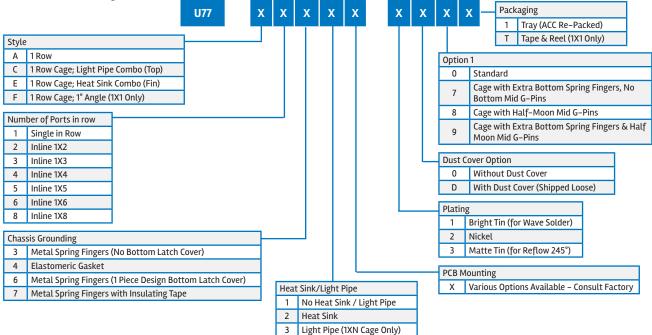
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ExpressPort® SFP+

ExpressPort[®] SFP+ Connector



ExpressPort® SFP+ Cage



ExpressPort® SFP+ 2XN (Cage/Connector)

		UE86	X	X	Х	X	X	Х	Х	Х	X	1 —	Packa 1	aging Tray	
Style B D K L S Num 1 2 3 3 4 5	2XN, No Light Pipe 2XN, Small Light Pipe Openings 2XN, Large Light Pipe Openings 2XN, Low Profile Combo (No Light Pipe) 2XN, Thermally Enhanced ber of Ports in row 2X1 Inline 2X2 Inline 2X3 Inline 2X4 Inline 2X5										1 2 3 Platin X Dust 0 0 D	Cover Without D	n n connector rus Option Dust Cover s Cover (Sh	ıs Available	actory
6 8	Inline 2X6 Inline 2X8										0 1 2	No Light F 4 Light Pi 2 Inner Lig	Pipe pes/2X1	/2X1	
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5 6 7	Elastomeric Gasket, Bottom Insulating T Metal Spring Fingers EMI Fingers, Bottom Insulating Tape	ape					L	 			7 A	ting Type: (Standard 2 Narrow Fla	XN Inge		HSIOEX PRESSPORT SFP0118EA4
Mour 2	nting Type: Connector Standard Press-Fit Pins (12Gbps)										С	Enhanced I	EMI		SSPORTS
5 A	Small Press-Fit Pins for High Speed Term Press-Fit Pins (10Gbps)	ination (16Gbp	5)												SIOEXPRE

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Disclaimer

Please note that the above information is subject to change without notice.